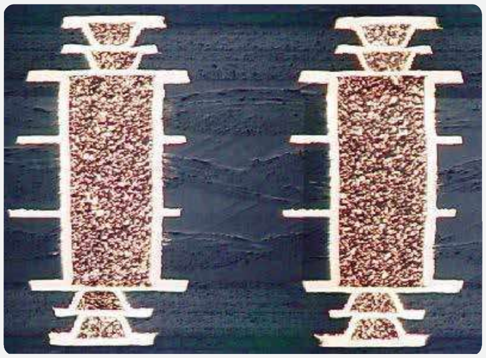
Conductive Via Filling Paste

Widely applicable from consumer electronics to industrial equipment

Applications

Heat release/inter-layer connection



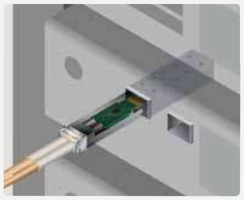
Cross-section

Consumer electronics

e.g. : SSD

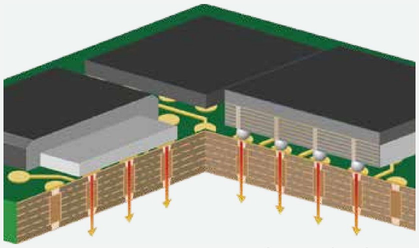
Telecommunication equipment

e.g. : Photonics tranceiver



Features

- Excellent adhesion to various material surfaces including copper foil
- Stable electrical conductivity
- High heat release (AE7332: 38W/m・k)
- Solvent-free enabling void/crack-free
- Contribution to high-density routing and/or multi-layer build-up
- Wide range line-up for your needs



Thermal release

Product line-up & properties

Product			AE1244	AE2217	AE1650	AE3030	AE7332
Viscosity	BH type	dPa・s	800 - 1,400	1,600 - 2,200	1,300 - 1,800	1,200 - 1,800	900 - 1,500
Curing conditions	Pre-curing		80℃×30min.	60℃×30min.	80℃×30min.	60℃×30min.	80℃×30min.
	Post-curing		160℃×60min.				
Volume resistivity (Representative value)		Ω・cm	1.0E-04			2.0E-04	5.0E-05
Thermal conductivity (Laser flash method)		W/m・k	11.7	13.5	16.5	7.8	38
Glass-transition temperature/Tg		℃	110	113	95	171	56

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